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April 2015

FDBL0210N80

N-Channel PowerTrench® MOSFET **80 V, 240 A, 2.0 m**Ω

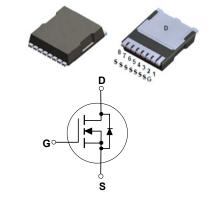
Features

- Typical $R_{DS(on)}$ = 1.5 mΩ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 130 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automations
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at http://www.fairchildsemi.com/dwg/PS/PSOF08A.pdf.

MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain-to-Source Voltage		80	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	240	A
I _D	Pulsed Drain Current	T _C = 25°C	See Figure 4	A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	512	mJ
D	Power Dissipation		357	W
P_{D}	Derate Above 25°C		2.38	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.42	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

- 1: Current is limited by silicon.
- Starting T_J = 25°C, L = 0.25mH, I_{AS} = 64A, V_{DD} = 80V during inductor charging and V_{DD} = 0V during time in avalanche.
 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0210N80	FDBL0210N80	MO-299A	-	-	-

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Units

Max.

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Characteristics								
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$,	80	-	-	٧		
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =80V,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	-	1	μА	
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA	
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA	

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.5	2.0	$m\Omega$
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	3.1	4.1	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	.,	V _{DS} = 40V, V _{GS} = 0V, f = 1MHz		10000	-	pF
C _{oss}	Output Capacitance				1540	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112			70	-	pF
R_{g}	Gate Resistance	f = 1MHz	f = 1MHz		2.8	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 64V	-	130	169	nC
Q _{g(th)}	Threshold Gate Charge	V _{GS} = 0 to 2V	V _{GS} = 0 to 2V I _D = 80A		18	27	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	47	-	nC
Q _{gd}	Gate-to-Drain "Miller" Charge			-	24	-	nC

Switching Characteristics

						1
t_{on}	Turn-On Time		-	-	133	ns
t _{d(on)}	Turn-On Delay		-	39	-	ns
t _r	Rise Time	$V_{DD} = 40V, I_{D} = 80A,$	-	63	-	ns
t _{d(off)}	Turn-Off Delay	$V_{GS} = 10V, R_{GEN} = 6\Omega$	-	61	-	ns
t _f	Fall Time		-	33	-	ns
t _{off}	Turn-Off Time		-	-	140	ns

Drain-Source Diode Characteristics

V _{SD}	Source-to-Drain Dioge Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	83	108	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =64V	-	118	153	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

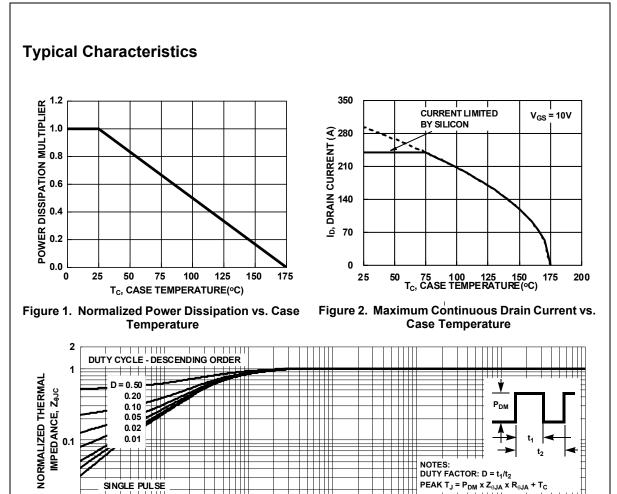
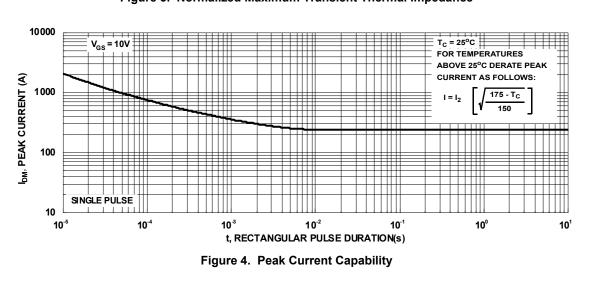


Figure 3. Normalized Maximum Transient Thermal Impedance

10⁻²

t, RECTANGULAR PULSE DURATION(s)

10⁻³



0.01 [∟] 10⁻⁵

10⁻⁴

10°

10¹

Typical Characteristics 2000 1000 If R = 0 $t_{AV} = (L)(I_{AS})/(1.3*RATED BV_{DSS} - V_{DD})$ 1000 € DRAIN CURRENT (A) $t_{AV} = (L/R)ln[(l_{AS}*R)/(1.3*RATED BV_{DSS} - V_{DD}) +1]$ AS, AVALANCHE CURRENT 100 100 10 STARTING T_J = 25°C OPERATION IN THIS AREA MAY BE LIMITED BY IDS (on) ئے SINGLE PULSE TJ = MAX RATED TC = 25°C 100ms 0.1 0.001 100 0.01 10 1000 0.1 10 100 tav, TIME IN AVALANCHE (ms) V_{DS}, DRAIN TO SOURCE VOLTAGE (V) NOTE: Refer to Fairchild Application Notes AN7514 and AN7515 Figure 5. Forward Bias Safe Operating Area Figure 6. Unclamped Inductive Switching Capability 350 400 PULSE DURATION = 80 µs IS, REVERSE DRAIN CURRENT (A) DUTY CYCLE = 0.5% MAX 300 V_{GS} = 0 V 100 V_{DD} = 5V € , DRAIN CURRENT (001 120 100 220 250 T_J= 175 °C 10 $T_J = 25^{\circ}C$ $T_J = 25$ °C T_J = -55°C $T_J = 175^{\circ}C$ ف 50 0.1 0.0 0.2 0.4 0.6 8.0 1.0 1.2 V_{GS}, GATE TO SOURCE VOLTAGE (V) V_{SD}, BODY DIODE FORWARD VOLTAGE (V) Figure 7. Transfer Characteristics Figure 8. Forward Diode Characteristics 350 350 VGS V_{GS} €300 €300 10V 8V 10V DRAIN CURRENT (0 00 02 05 00 05 05 7V 7V 5V 5V 80μs PULSE WIDTH 80µs PULSE WIDTH Tj=25°C ڡٛ Tj=175°C 50 50 0 0 Figure 9. Saturation Characteristics Figure 10. Saturation Characteristics

I_D = 80A 30

Typical Characteristics

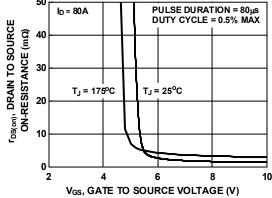


Figure 11. R_{DSON} vs. Gate Voltage

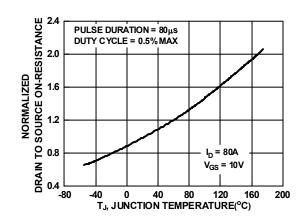


Figure 12. Normalized $R_{\mbox{\footnotesize DSON}}$ vs. Junction Temperature

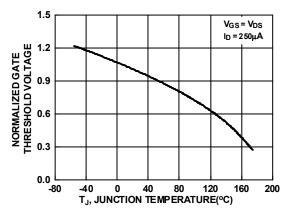


Figure 13. Normalized Gate Threshold Voltage vs. **Temperature**

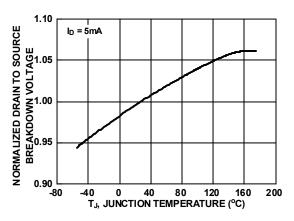


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

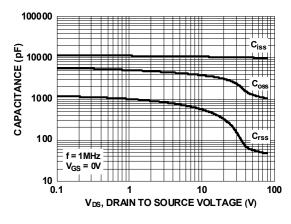


Figure 15. Capacitance vs. Drain to Source Voltage

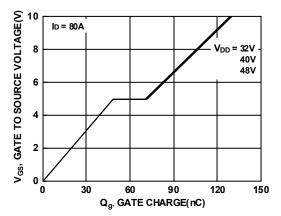
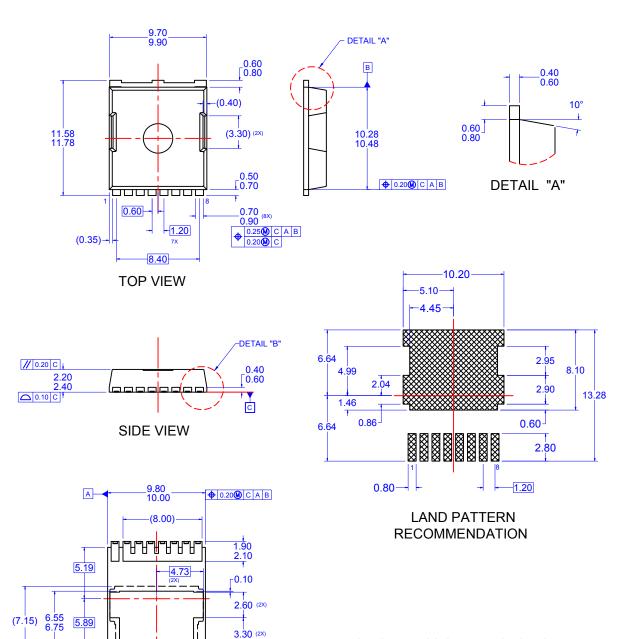


Figure 16. Gate Charge vs. Gate to Source Voltage



NOTES: UNLESS OTHERWISE SPECIFIED

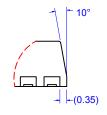
- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

BOTTOM VIEW

7.60

- - 1.20

3.75



0.65-

DETAIL "B"

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